

NOTES, UNLESS OTHERWISE SPECIFIED:

1. The netname "V5P0V" represents connection to the +5.0V power buss.
2. The netname "V5P0VF" represents connection to the +5.0V filtered power buss.
3. The netname "V3P3V" represents connection to the +3.3V power buss
4. The netname "V2P5VREF" represents connection to the +2.5V reference buss
5. The netname "V2P5VREFBUF" represents connection to the +2.5V buffered reference buss.
6. The netname "GND" represents connection to the ground plane.
7. A "Z" suffix on a signal name indicates an active low signal.
8. All components with designators "U\*", "Q\*", and "D\*" are electrostatic discharge sensitive.
9. All resistor values are in ohms.
10. All capacitor values in microfarads unless otherwise specified.



COMPUTER GENERATED DRAWING - DO NOT REVISE MANUALLY

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
-	Draft Release	04/16/2014	HPC
A	ECO 2141383: REV A Release	05/22/2014	HPC

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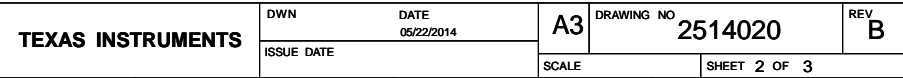
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		ENGR		05/22/2014					
		APVD		05/22/2014					
		MFG				TITLE ESD, Mobile Spectroscopy Detector Board			
	0314CP	QA							
NEXT ASSY	USED ON				A3	DRAWING NO	2514020	REV	B
APPLICATION		SW	Allegro Design Entry 16.6			SCALE		SHEET 1 of 3	



Revision History

Rev. -- : Draft Release ~ 04/16/2014

Rev. A: ECO 2141383: ~ 05/22/2014

Rev. B: C9, C17 change value to 51pF, C15 change value to 47nF: ~ 11/03/2014 MR.

Schematic Revision History

TEXAS INSTRUMENTS	DWN	DATE	A3	DRAWING NO	2514020	REV	B
	05/22/2014						
	ISSUE DATE		SCALE		SHEET 3 OF 3		